

HAT2191WP

Silicon N Channel Power MOS FET Power Switching

REJ03G1223-0500

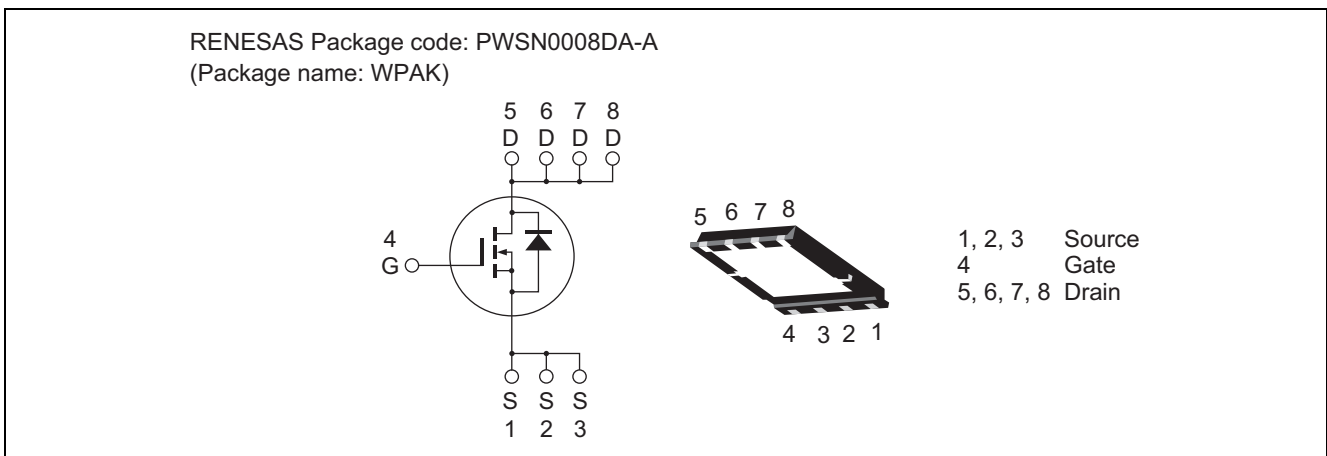
Rev.5.00

Jun.02.2005

Features

- Low on-resistance
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	250	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I_D	14	A
Drain peak current	$I_{D(pulse)}$ ^{Note1}	28	A
Body-drain diode reverse drain current	I_{DR}	14	A
Body-drain diode reverse drain peak current	$I_{DR(pulse)}$ ^{Note1}	28	A
Avalanche current	I_{AP} ^{Note3}	7	A
Avalanche energy	E_{AR} ^{Note3}	3.0	mJ
Channel dissipation	P_{ch} ^{Note2}	30	W
Channel to case thermal impedance	θ_{ch-c}	4.17	°C/W
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Notes: 1. $PW \leq 10 \mu s$, duty cycle $\leq 1\%$

2. Value at $T_c = 25^\circ C$

3. $ST_{ch} = 25^\circ C$, $T_{ch} \leq 150^\circ C$

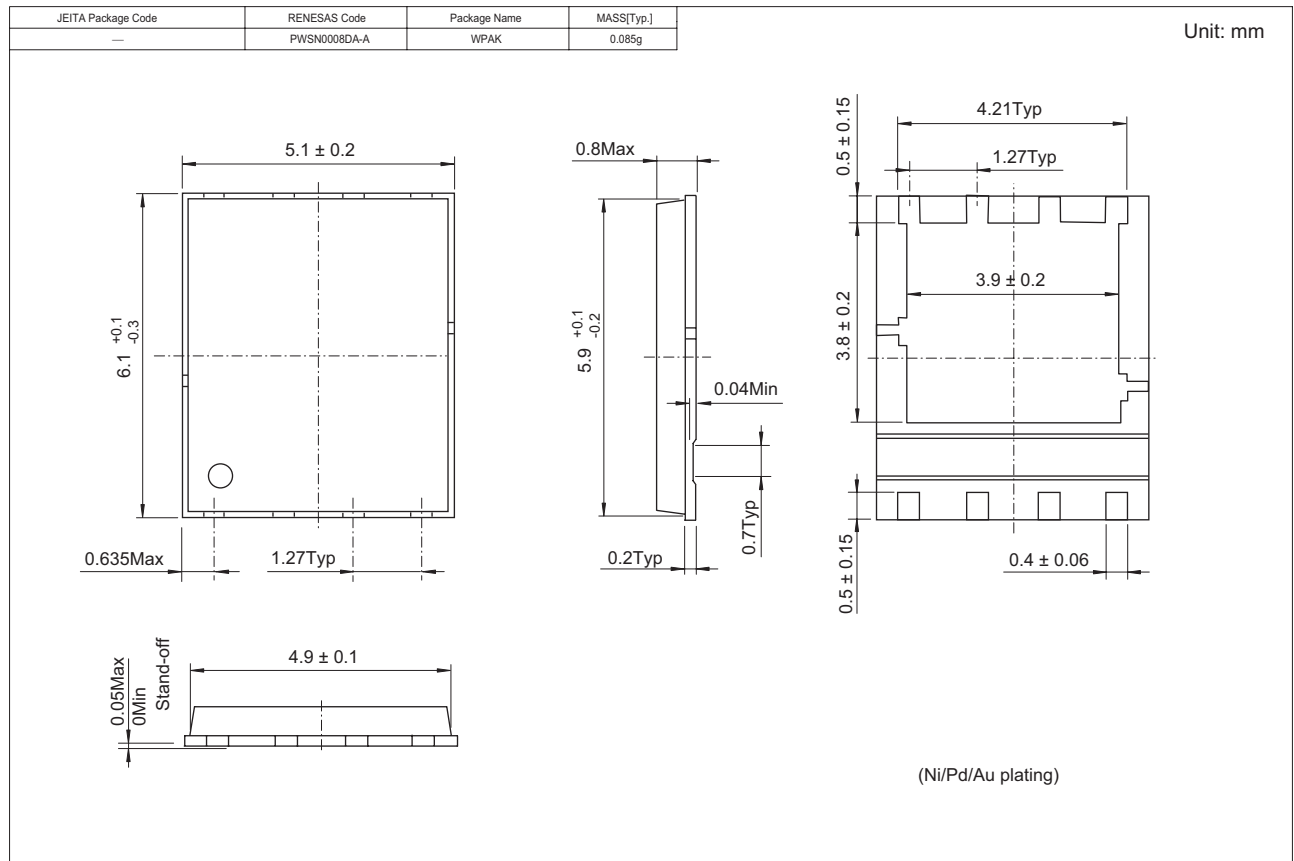
Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	250	—	—	V	$I_D = 10 \text{ mA}$, $V_{GS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 250 \text{ V}$, $V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 0.1	μA	$V_{GS} = \pm 30 \text{ V}$, $V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	—	4.5	V	$V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$
Forward transfer admittance	$ y_{fs} $	7	12	—	S	$I_D = 7 \text{ A}$, $V_{DS} = 10 \text{ V}$ ^{Note4}
Static drain to source on state resistance	$R_{DS(on)}$	—	0.120	0.138	Ω	$I_D = 7 \text{ A}$, $V_{GS} = 10 \text{ V}$ ^{Note4}
Input capacitance	C_{iss}	—	1200	—	pF	$V_{DS} = 25 \text{ V}$
Output capacitance	C_{oss}	—	185	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	14	—	pF	$f = 1 \text{ MHz}$
Turn-on delay time	$t_{d(on)}$	—	30	—	ns	$I_D = 7 \text{ A}$
Rise time	t_r	—	45	—	ns	$V_{GS} = 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	60	—	ns	$R_L = 25 \Omega$
Fall time	t_f	—	15	—	ns	$R_g = 17.9 \Omega$
Total gate charge	Q_g	—	27	—	nC	$V_{DD} = 200 \text{ V}$
Gate to source charge	Q_{gs}	—	7	—	nC	$V_{GS} = 10 \text{ V}$
Gate to drain charge	Q_{gd}	—	10	—	nC	$I_D = 14 \text{ A}$
Body-drain diode forward voltage	V_{DF}	—	0.86	1.40	V	$I_F = 14 \text{ A}$, $V_{GS} = 0$ ^{Note4}
Body-drain diode reverse recovery time	t_{rr}	—	150	—	ns	$I_F = 14 \text{ A}$, $V_{GS} = 0$ $diF/dt = 100 \text{ A}/\mu\text{s}$

Notes: 4. Pulse test

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Ordering Information

Part Name	Quantity	Shipping Container
HAT2191WP-EL-E	2500 pcs	Taping

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Unit2607 Ruijing Building, No.205 Maoming Road (S), Shanghai 200020, China
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